

Electronic Acknowledgement Receipt

EFS ID:	1054356
Application Number:	10632552
Confirmation Number:	2572
Title of Invention:	Semiconductor multi-package module having package stacked over die-up flip chip ball grid array package and having wire bond interconnect between stacked packages
First Named Inventor:	Marcos Karnezos
Customer Number:	22470
Filer:	Bill Kennedy/Paula Hurley
Filer Authorized By:	Bill Kennedy
Attorney Docket Number:	CPAC 1017-5
Receipt Date:	22-MAY-2006
Filing Date:	02-AUG-2003
Time Stamp:	18:20:52
Application Type:	Utility
International Application Number:	

Payment information:

Submitted with Payment	yes
Payment was successfully received in RAM	\$ 630
RAM confirmation Number	369
Deposit Account	

File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
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1		efsmpids.pdf	488859	yes	14
	Multipart Description				
	Doc Desc		Start	End	
	Amendment - After Non-Final Rejection		1	1	
	Claims		2	5	
	Applicant Arguments/Remarks Made in an Amendment		6	11	
	Information Disclosure Statement (IDS) Filed		12	14	
Warnings:					
Information:					
2	Fee Worksheet (PTO-875)	fee-info.pdf	8382	no	2
Warnings:					
Information:					
Total Files Size (in bytes):			497241		
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p><u>New Applications Under 35 U.S.C. 111</u> If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><u>National Stage of an International Application under 35 U.S.C. 371</u> If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p>					